

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: _____ SAW FILTER _____
MODEL NO 型号: _____ HDF92M SMD-24 _____
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ D A T E 日期: _____ 2006-3-22 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. SCOPE

This specification shall cover the characteristics of SAW filter 92.025MHz with used for remote-control security.

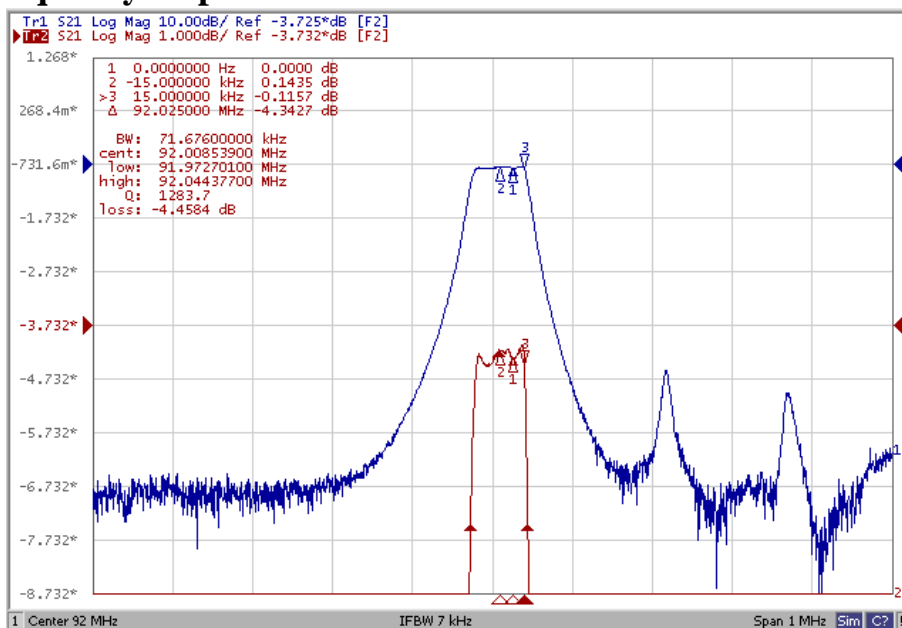
2. ELECTRICAL SPECIFICATION

DC Voltage VDC 10V	
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

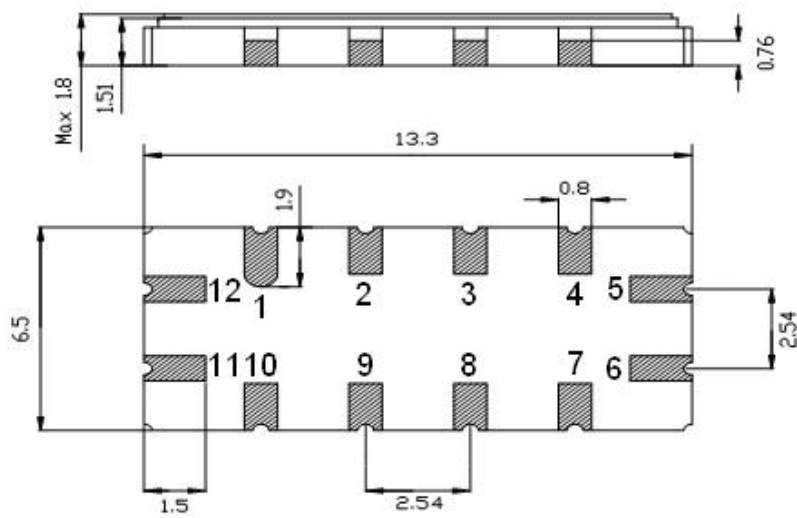
2-1. Electrical characteristics

Item	Specification
Center Frequency	92.025
Insertion Loss	5.5dB max
-1dB Passwidth	20 KHz min, 50 KHz typ
-3dB Passwidth	30 KHz min, 60 KHz typ
Pass Band Ripple(+/-15KHz)	1.0 dB max
Fc+/-100 KHz	32.0 dB min.
Fc+200KHz~+500KHz	22.0 dB min.
Fc+500KHz~+1000KHz	37.0dB min..
Fc-300KHz~-900KHz	52.0 dB min.
Fc-900KHz~-920KHz	56.0dB min..
Fc-920KHz~-1000KHz	52.0dB min..
Input power	0 dBm
Group delay variation(+/-15KHz)	4μs pk-pk

2.2. Typical frequency response

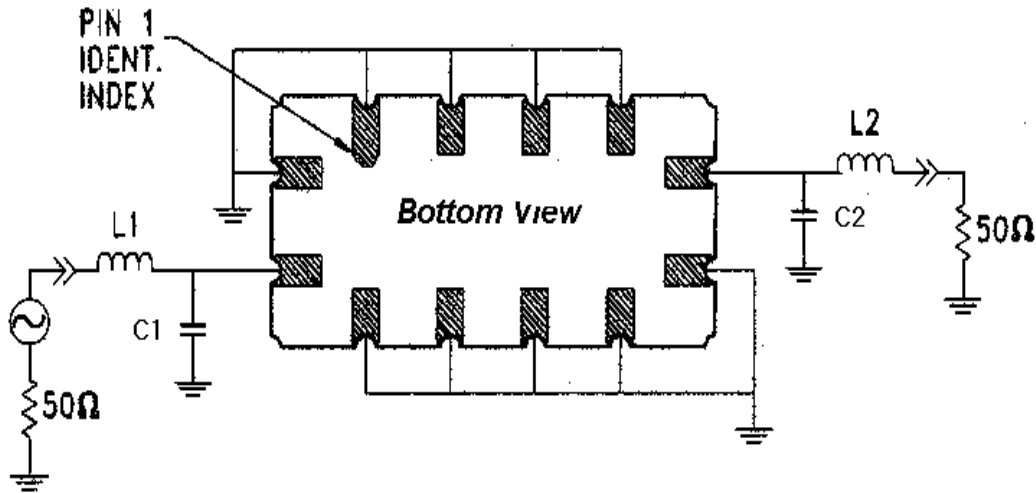


3. DIMENSION



All dimension tolerance <math><0.2\text{mm}</math>

4. TEST CIRCUIT



$$L1=L2=390nH, \quad C1=3pF \quad C2=2.7pF$$

5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-1.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-1.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2-1.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-1.

5-5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2-1.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2-1.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-1.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.